



Customer Information Notification

201911009I

Issue Date: 13-Dec-2019

Effective Date: 14-Dec-2019

Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#)

This notice is NXP Company Proprietary.



Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input checked="" type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

LQFP64 High Density Leadframe Conversion in TFME

Description

NXP Semiconductors announces the LQFP 10x10 64L lead frame conversion from standard matrix configuration to High Density configuration for the TongFu Microelectronics Co., Ltd. Nantong China assembled devices associated with this notification. No change to lead frame materials. There is a change on internal appearance with lead frame flag size has increased to 268 x 268 mils. No change on external appearance and case outline.

Reason

LQFP 10x10 64L high density lead frame conversion is required for manufacturing standardization and capacity / utilization improvement.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Additional documents: [view online](#)



Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Fusheng Zhai

Position Product Engineer

e-mail address fusheng.zhai@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

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NXP Semiconductors

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